Next week are acceptance tests at Finetech

- DESY‘s Femto is ready at Finetech
- Goal is to build two new dummy modules with DESY‘s Femto
- Installation of the Femto at DESY is planned for February 2013

- (SB2-Jet installation is planned for April 2013)
- Pac Tech offers **5 sensor wafer** processing for ~ **11 k€**

  This includes solder balling of
  - 2 sensor modules
  - 10 single sensors

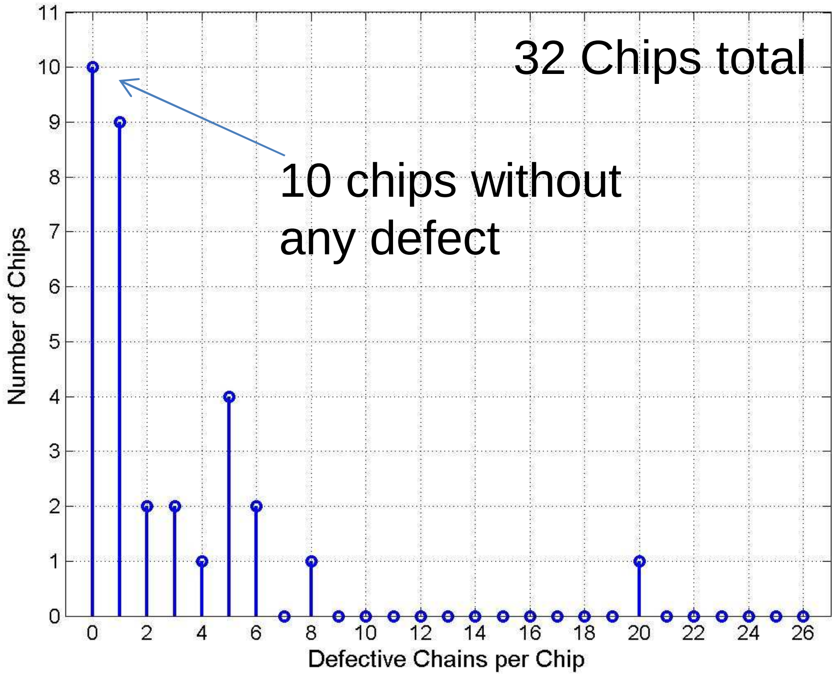
  $\left.\begin{array}{l} \\ \\ \end{array}\right\}$ 1 wafer

- VTT process strongly delayed (delivery still this year?)

Dummy Module 2 was measured again with improved alignment of the probecard

COMPLETE RESULTS OF MODULE 1 **AND** 2

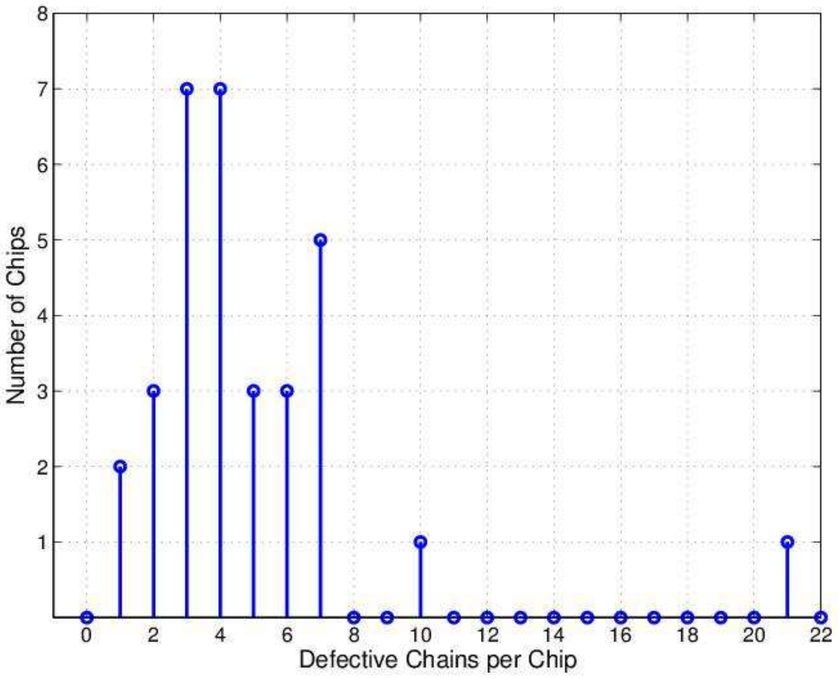
NEW



32 Chips total

10 chips without any defect

OLD

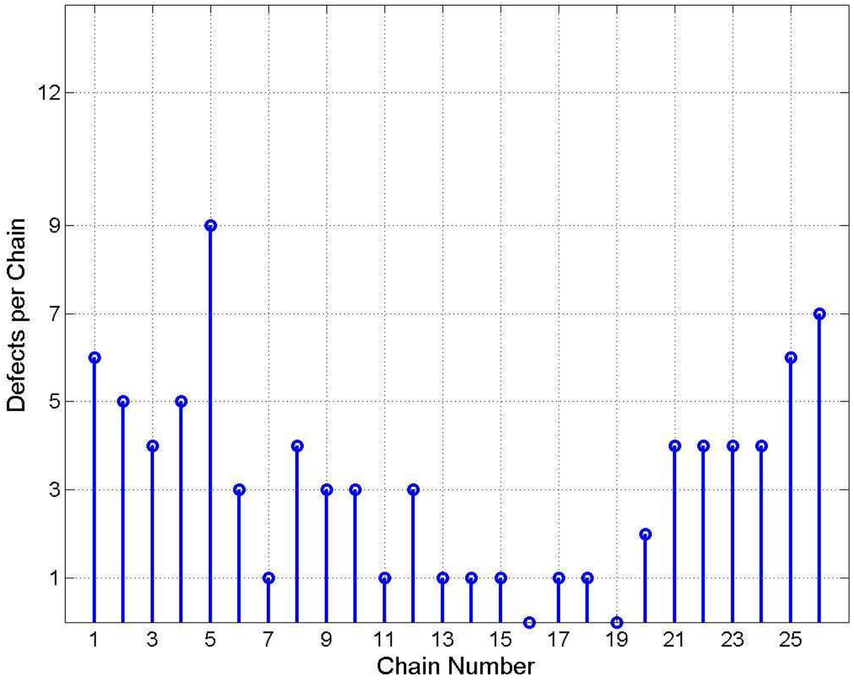


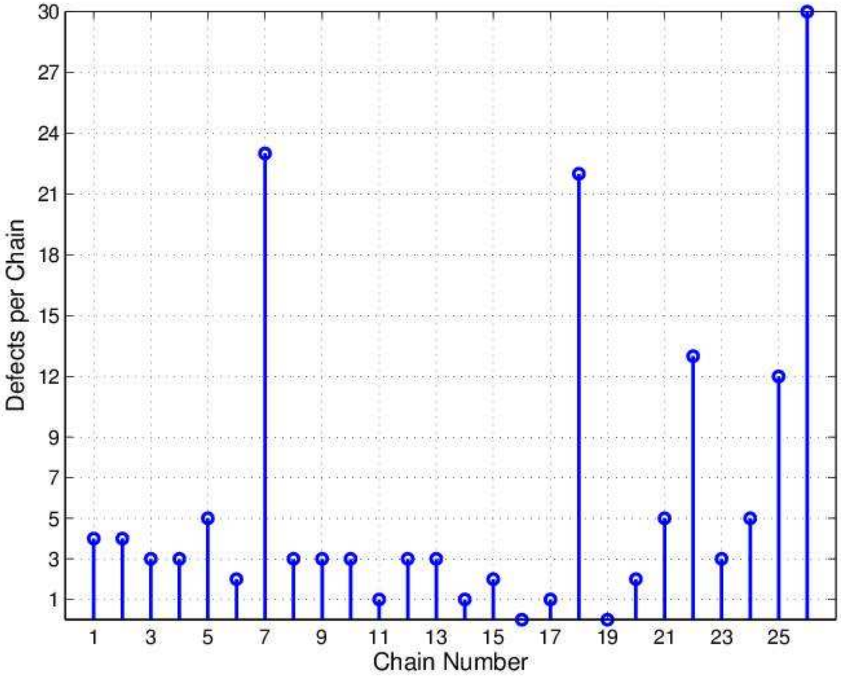
Improvements:

- 90 % of the chains work
- 83 defective chains → 0.06 % bad bumps?

Dummy Module 2 was measured again with improved alignment of the probecard

COMPLETE RESULTS OF MODULE 1 **AND** 2


NEW


OLD

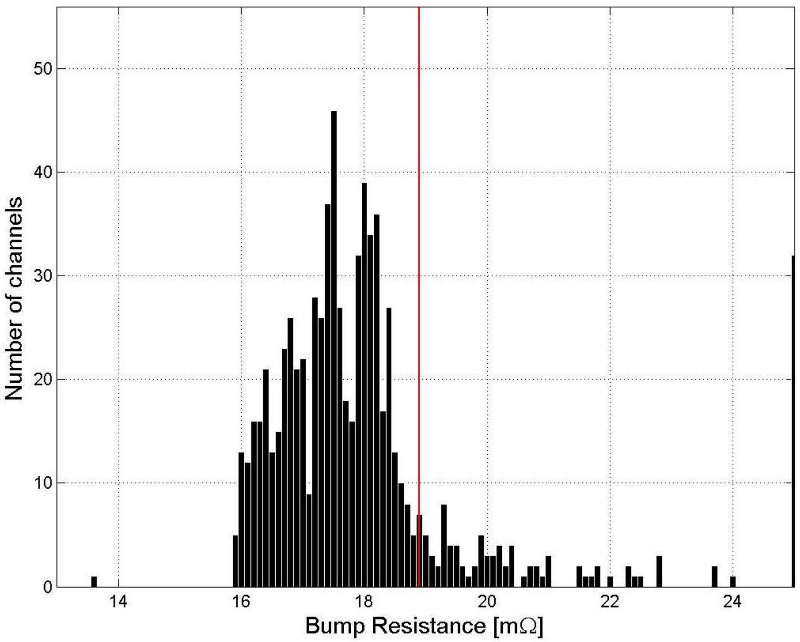
Improvements:

- Increase of defect towards chip edge much less distinct

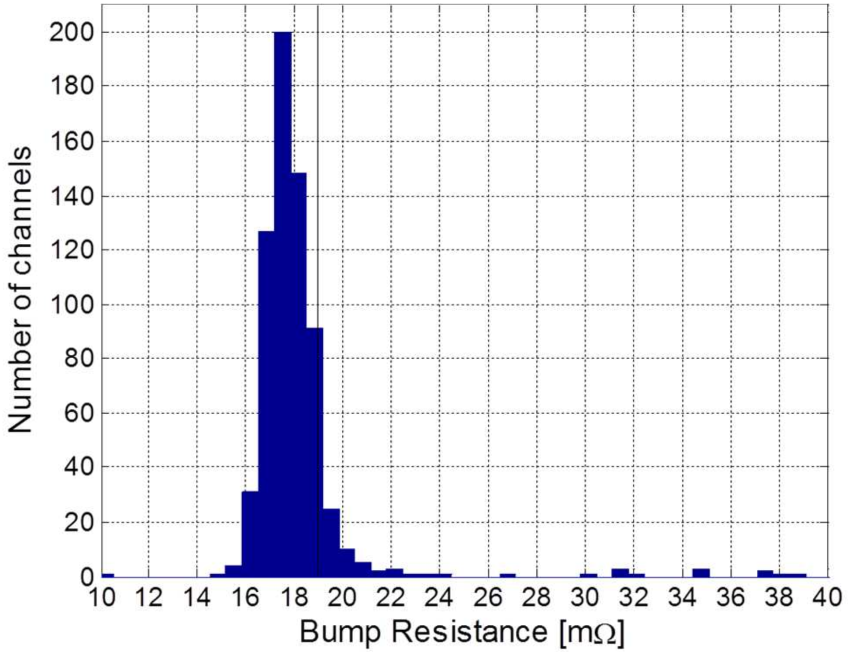
Dummy Module 2 was measured again with improved alignment of the probecard

COMPLETE RESULTS OF MODULE 1 **AND** 2

NEW



OLD



There is no difference in the mean bump resistance

Peak @ 18 mΩ